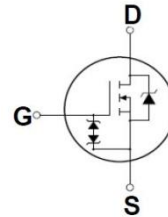
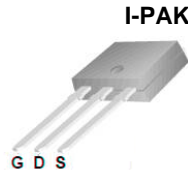


Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification

BV_{DSS}	I_D	$R_{DS(on)}$
500V	2.5A	<2.8W



Device	Package	Marking	Remark
TMD3N50Z / TMU3N50Z	D-PAK/I-PAK	TMD3N50Z / TMU3N50Z	RoHS
TMD3N50ZG / TMU3N50ZG	D-PAK/I-PAK	TMD3N50ZG / TMU3N50ZG	Halogen Free

Absolute Maximum Ratings

Parameter	Symbol	TMD3N50Z(G)/TMU3N50Z(G)	Unit
Drain-Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GS}	30	V
Continuous Drain Current	I_D	$T_C = 25$	A
		$T_C = 100$	A
Pulsed Drain Current ^(Note 1)	I_{DM}	10	A
Single Pulse Avalanche Energy ^(Note 2)	E_{AS}	107	mJ
Repetitive Avalanche Current ^(Note 1)	I_{AR}	2.5	A
Repetitive Avalanche Energy ^(Note 1)	E_{AR}	5.2	mJ
Power Dissipation	P_D	$T_C = 25$	W
		Derate above 25	W/
Peak Diode Recovery dv/dt ^(Note 3)	dv/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	
Maximum lead temperature for soldering purposes,	T_L	300	

* Limited only by maximum junction temperature

Thermal Characteristics

Parameter	Symbol	TMD3N50Z(G)/TMU3N50Z(G)	Unit
Maximum Thermal resistance, Junction-to-Case	R_{qJC}	2.4	/W
Maximum Thermal resistance, Junction-to-Ambient	R_{qJA}	110	/W

Electrical Characteristics : $T_C=25$, unless otherwise noted

Parameter	Symbol	Test condition	Min	Typ	Max	Units
OFF						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	500	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
Forward Gate-Source Leakage Current	I_{GSSF}	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	\square	100	μA
Reverse Gate-Source Leakage Current	I_{GSR}	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	TJEFBT/F1	100	μA

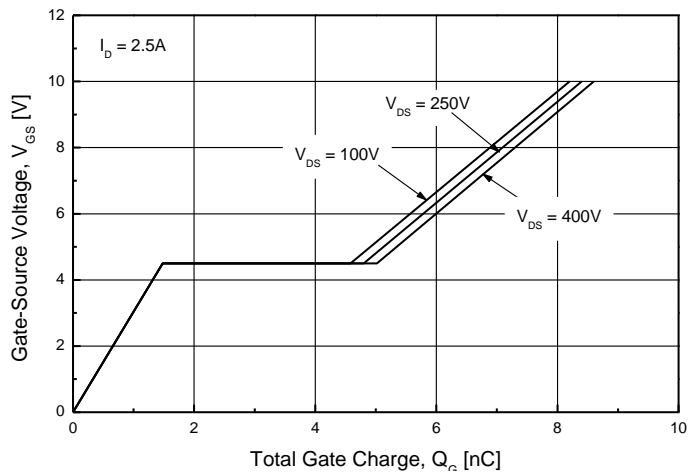
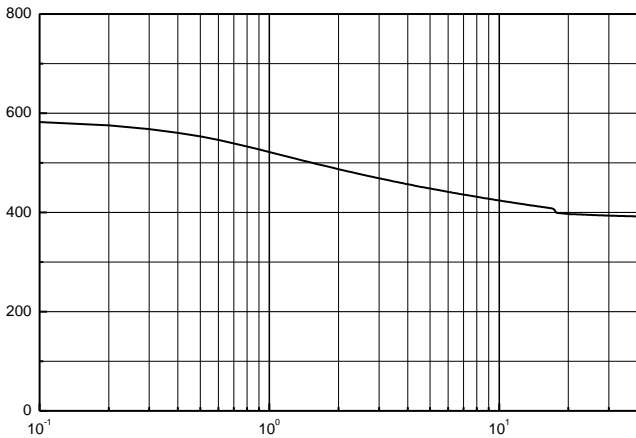
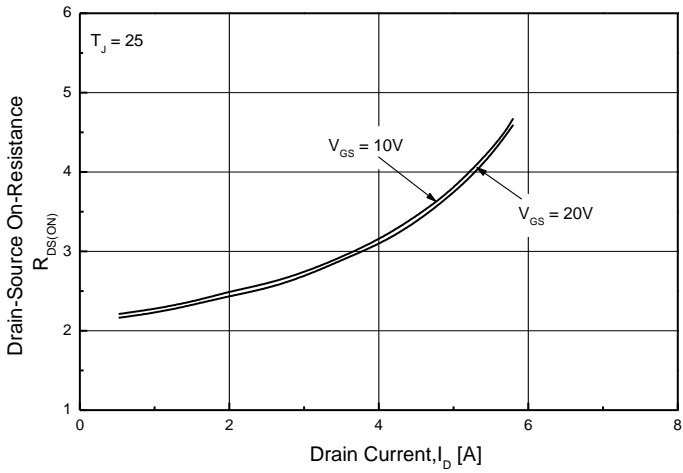
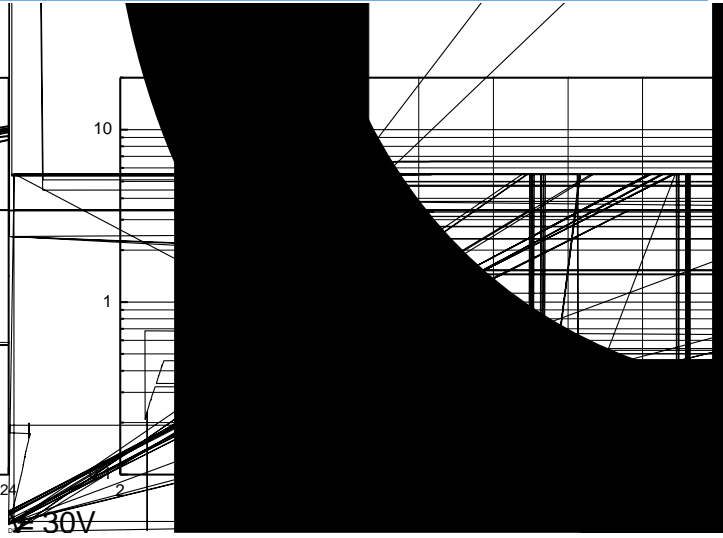
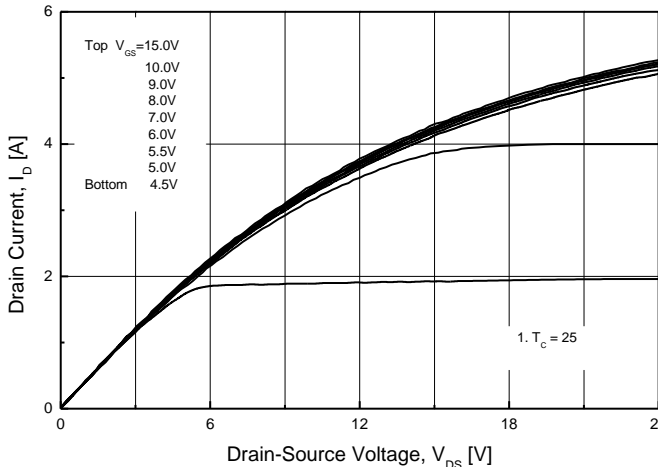
ON						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2	--	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 1.25\text{ A}$	--	2.3	2.8	Ω
Forward Transconductance ^(Note 4)	g_{FS}	$V_{DS} = 30\text{ V}, I_D = 1.25\text{ A}$	--	5	--	S

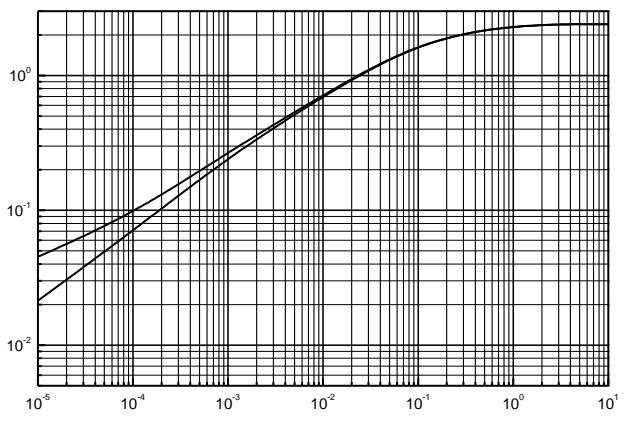
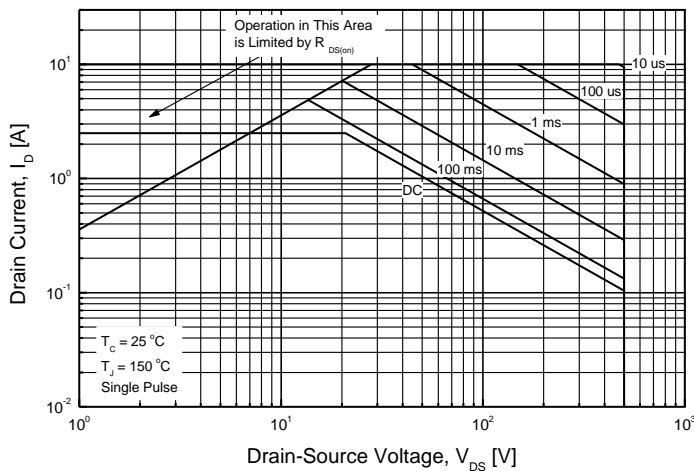
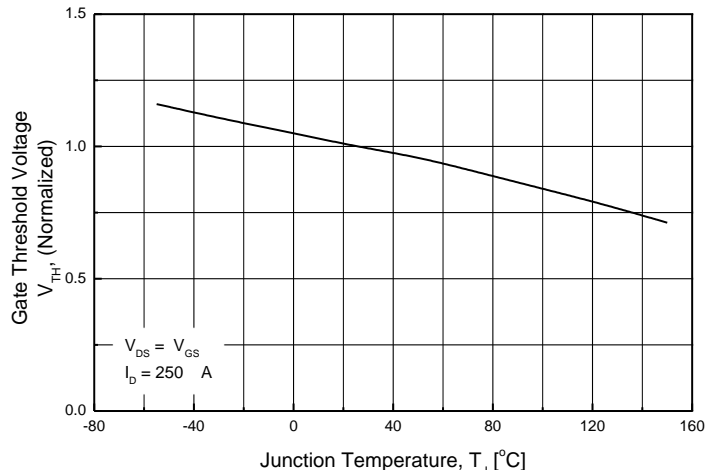
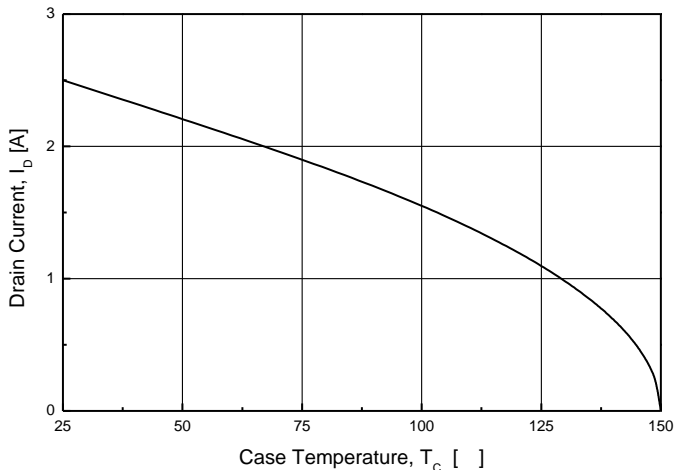
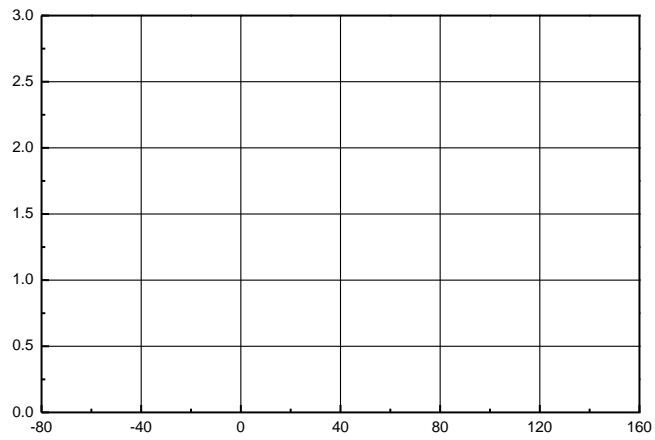
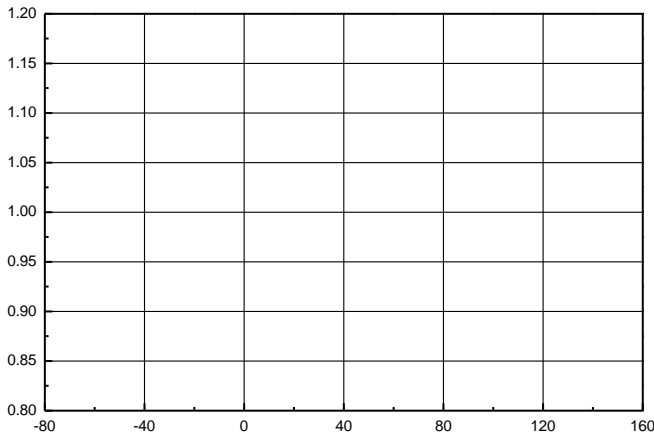
DYNAMIC						
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	395	--	pF
Output Capacitance	C_{oss}		--	44	--	pF
Reverse Transfer Capacitance	C_{rss}		--	7.8	--	pF

SWITCHING						
Turn-On Delay Time ^(Note 4,5)	$t_{d(on)}$	$V_{DD} = 250\text{ V}, I_D = 2.5\text{ A},$ R_G	--	16	--	ns
Turn-On Rise Time ^(Note 4,5)	t_r					

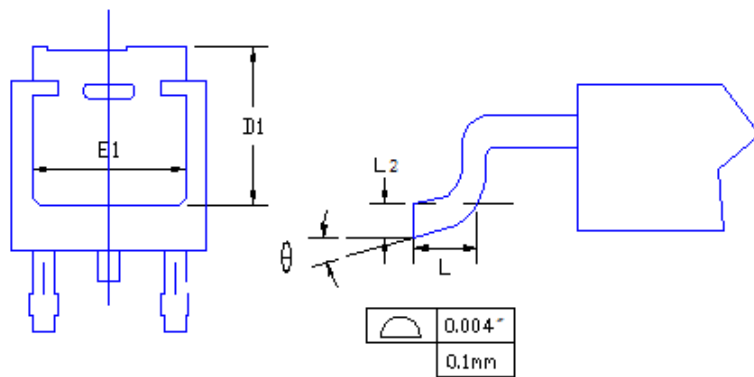
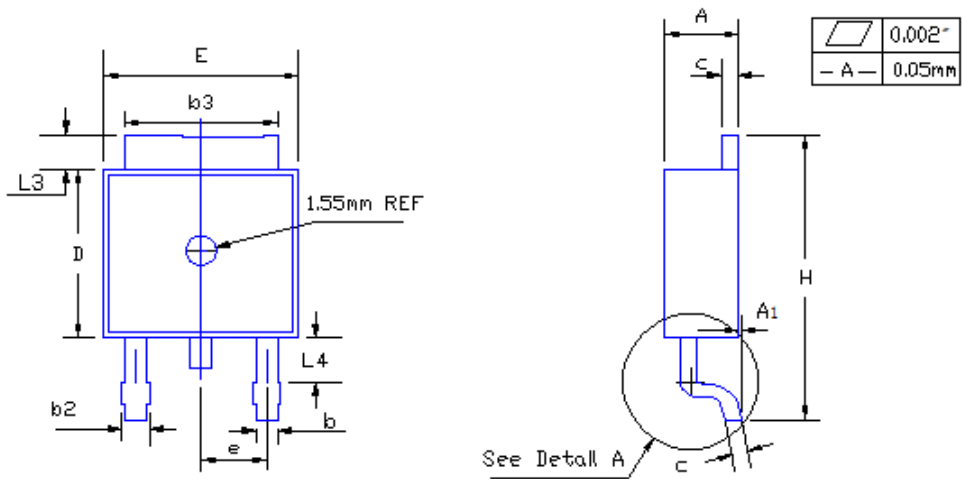
- Note :
- Repeated rating : Pulse width limited by safe operating area
 - $L=30.9\text{mH}, I_{AS} = 2.5\text{A}, V_{DD} = 50\text{V}, R_G = 25$, Starting $T_J= 25$
 - I_{SD} , di/dt $\mu\text{s}, V_{DD}$ $\mu\text{s}, V_{DS}$, Starting $T_J= 25$
 - Essentially Independent of Operating Temperature Typical Characteristics

TMD3N50Z(G)/TMU3N50Z(G)



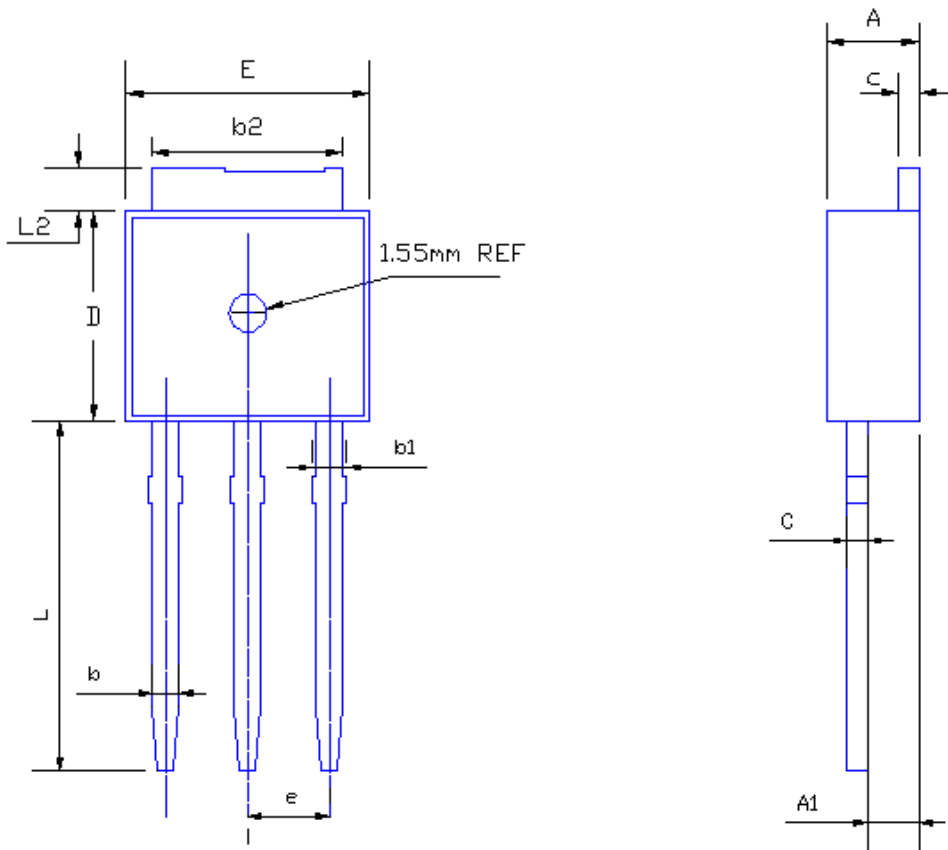


TO-252 (D-PAK) MECHANICAL DATA



SYMBOL	MILLIMETERS	
	MIN	MAX
A	2.19	2.38
A1	—	0.13
b	0.64	0.89
b2	0.84	1.14
b3	5.21	5.46
c	0.46	0.61
D	5.97	6.22
D1	5.21	—
E	6.35	6.73
E1	4.83	—
e	2.29BSC	
H	9.65	10.41
L	1.40	1.78
L2	0.51BSC	
L3	0.89	1.27
L4	0.64	1.01
θ	0	8

TO-251 (I-PAK) MECHANICAL DATA



SYMBOL	MILLIMETERS	
	MIN	MAX
A	2.19	2.38
A1	1.04	1.23
b	0.64	0.89
b1	0.84	1.14
b2	5.23	5.48
c	0.46	0.61
D	5.91	6.28
E	6.21	6.59
e	2.28 TYP	
L	8.89	9.65
L2	0.89	1.27